Optimized system-on-chip processor, DACs and ADCs for defense digitizer systems

🕂 Texas Instruments

This **TI Design** is for developers currently leveraging an FPGA or ASIC in their product solution with high-speed ADCs and DACs. Significant time savings are achieved by pre-integrating hardware and software for both the processor and ADC/DAC. Additionally, this solution saves cost, power and size versus a traditional FPGA-based solution. The design includes the first widely available processor integrating a JESD204B interface and Digital Front End (DFE), the **66AK2L06** SoC. Connecting the **ADC12J4000** and **DAC38J84** to the 66AK2L06 processor provides an efficient solution for test and measurement and defense applications.

Features

- Easy integration of signal processor to data converters over JESD204B
- Multichannel sampling rates up to 368Msps with 150MHz of processing bandwidth
- DFE processing for filtering, down-sampling or up-sampling
- Wideband sampling with JESD204B attached signal processing solution including DSP, ADC and DAC boards, demo software, configuration GUIs and getting started guide
- A robust demonstration and development platform including three EVMs, a deterministic latency card, schematic, BOM, user guide, benchmarks, software and demos
- New TI Design for synthetic aperture radar (SAR) applications coming soon (shown to the right)

Visit: www.ti.com/tidesign0034





Coming soon: TI Design demonstrating an optimized SAR application using an on-chip FFT coprocessor

TX Signal Capture @ DSP (4k FFT, Hanning)



Web interface for control and visualization

TI products in the TI Design

66AK2L06 system-on-chip

- Integrated DFE technology with programmable up/down sampling and filtering
- Latency optimization using 2× FFT coprocessors up to 8K-points and >80dB SNR. 35 GFLOPS @ 8K
- Four TMS320C66x DSP cores with fixedand floating-point processing providing 153.6GMACS and 76.8GFLOPS
- Two ARM[®] Cortex[®]-A15 RISC cores providing 8400 DMIPS
- Floating-point FFT with TMS320C66x DSP any size FFT, >300dB SNR, 4GFLOPS @8K

Combined RX Signal Capture @DSP



Software Programmable Digital Front End (DFE)



Frequency Plan

- Max sample rate: 368Msps TX and 368Msps RX complex
- 330MHz instantaneous and 150MHz occupied signal bandwidth

Input / Output

- 4× JESD204B lanes, 7.4Gbps each
- 4RX and 4TX streams
- 4 streams and 4/8/12 DDUC channels on each
- stream 18-bit data path

resolution

Performance

- > 90dB stopband performance
- Programmable FIR with 399 taps maximum tap length
- 1–16 integer decimation rates
- Fractional decimation using resampling



DAC38J84: Quad 16-bit 2.5-GSPS DAC

- Low power: 450 mW/ch @ 2.5GSPS
- JESD204B, 8 lanes 12.5-Gbps interface
- 10×10mm, 0.8-mm pitch BGA

ADC12J4000: 12-bit 4-GSPS ADC

- RF sampling to > 3GHz
- JESD204B, 8 lanes 10-Gbps interface

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